



Material Content Data Sheet



Sales Product Name				TDA21231		Issued		20. July 2018	
MA#				MA001242592					
Package				PG-IQFN-31-2		Weight*		72.50 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.540	2.12	2.12	21238	21238	
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.00		48		
	non noble metal	zinc	7440-66-6	0.014	0.02		192		
	non noble metal	iron	7439-89-6	0.279	0.38		3844		
wire	non noble metal	copper	7440-50-8	11.316	15.61	16.01	156071	160155	
	non noble metal	copper	7440-50-8	0.099	0.14	0.14	1360	1360	
	encapsulation	organic material	carbon black	1333-86-4	0.059	0.08		818	
	plastics	epoxy resin	-	3.055	4.21		42135		
	inorganic material	silicondioxide	60676-86-0	26.546	36.62	40.91	366124	409077	
leadfinish	non noble metal	tin	7440-31-5	0.999	1.38	1.38	13776	13776	
plating	noble metal	silver	7440-22-4	0.054	0.07	0.07	741	741	
glue	plastics	epoxy resin	-	0.094	0.13		1290		
	noble metal	silver	7440-22-4	0.281	0.39	0.52	3871	5161	
solder	noble metal	silver	7440-22-4	0.026	0.04		353		
	non noble metal	tin	7440-31-5	0.051	0.07		707		
	non noble metal	lead	7439-92-1	0.948	1.31	1.42	13079	14139	
heatspreader	inorganic material	phosphorus	7723-14-0	0.005	0.01		73		
	non noble metal	zinc	7440-66-6	0.021	0.03		292		
	non noble metal	iron	7439-89-6	0.424	0.58		5849		
heat sink CLIP	non noble metal	copper	7440-50-8	17.220	23.75	24.37	237500	243714	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		39		
	non noble metal	zinc	7440-66-6	0.011	0.02		157		
	non noble metal	iron	7439-89-6	0.227	0.31		3135		
	non noble metal	copper	7440-50-8	9.230	12.73	13.06	127308	130639	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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